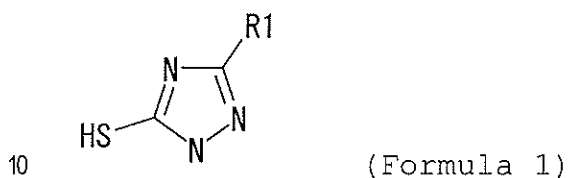


ABSTRACT OF THE DISCLOSURE

An epoxy resin composition for encapsulating a semiconductor comprising (A) an epoxy resin, (B) a phenolic resin,
5 (C) a hardening accelerator, (D) an inorganic filler and (E) a triazole compound, preferably an epoxy resin composition for encapsulating a semiconductor wherein the triazole compound is a compound represented by general formula (1).

[Chem. 1]



(wherein R1 represents hydrogen atom, or mercapto group, amino group, hydroxyl group or a hydrocarbon chain with 1 to 8 carbon atoms containing one or more of the functional groups as an end
15 group.)